

Major Terms of HKMC's HKD and CNH Bond Issue

Issuer:	The Hong Kong Mortgage Corporation Limited	
Expected Issue Rating:	AA+ (S&P) / Aa3 (Moody's)	
Issue Date:	9 February 2021	
	HKD Bond Issue	CNH Bond Issue
Issue Size:	HK\$7 billion	CNH2.5 billion
Maturity Date:	9 February 2023	9 February 2024
Tenor:	2 years	3 years
Coupon:	0.5% per annum	2.7% per annum
Status:	Senior and unsecured	
Listing:	The Stock Exchange of Hong Kong Limited	
Joint Global Coordinators, Joint Lead Managers and Joint Bookrunners:	Crédit Agricole Corporate and Investment Bank, The Hongkong and Shanghai Banking Corporation Limited and Standard Chartered Bank	
Joint Lead Managers and Joint Lead Bookrunners:	Australia and New Zealand Banking Group Limited, Bank of China (Hong Kong) Limited and Mizuho Securities Asia Limited	